



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGD10HF60KD	DMDP*CV63A62	A	SHENZHEN B/E	2015-09-04
Amount		UoM	Unit type	ST ECOPACK Grade
350.00		mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	Package: TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DMDP*CV63A62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	10.395	mg	supplier	die	Silicon (Si)	7440-21-3		10.147	mg	976140	28989
				supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	2694	80
				supplier	Passivation	Silicon Oxide	7631-86-9		0.036	mg	3464	103
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	289	9
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	289	9
				supplier	back side metallization	Gold (Au)	7440-57-5		0.017	mg	1636	49
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.067	mg	6446	191
				supplier	polymer die coating	Probimide	proprietary		0.094	mg	9044	269
Leadframe	Copper & its alloys	166.150	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	469006
				supplier	alloy	CopperPhosphorus (CuP)	12517-41-8		0.330	mg	1986	943
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1320
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3426
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	42	20
Soft solder	Solder	5.417	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	5.174	mg	955141	14783
				supplier	solder	Silver (Ag)	7440-22-4		0.135	mg	24922	386
				supplier	solder	Tin (Sn)	7440-31-5		0.108	mg	19937	309
Bonding wires	Other inorganic materials	0.803	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.803	mg	1000000	2294
Encapsulation	Other Organic Materials	166.190	mg	supplier	mold compound	Silica, vitreous	60676-86-0		133.950	mg	806005	382714
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		11.633	mg	69998	33237
				supplier	mold compound	Phenol resin	9003-35-4		6.648	mg	40002	18994
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		9.971	mg	59998	28489
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.994	mg	11998	5697
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.163	mg	6998	3323
				supplier	mold compound	Carbon black	1333-86-4		0.831	mg	5000	2374
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	2986